

High Temperature Masking Tape



Features:

- High temperature masking tape and dots are ideal for masking gold fingers of printed circuit boards during wave solder or solder dip process, as well as for solder wave masking and electrical insulation.
- This high temperature tape is a polyimide, pressure sensitive, adhesive tape with silicon resin, which shows excellent dielectric insulation properties, high heat resistance and excellent solvent resistance. These properties result in a tape with remarkable dimensional stability and excellent electrical and physical properties over a wide range of temperatures.
- This product is neither corrosive nor ozone depleting and is both flame and chemical resistant.



	DIN Value:	ASTM Value:
Structure	Silicone Adhesive / Polyimide Film	
Base Film Thickness	0.025mm	1.0MIL
Total Thickness	0.070mm	2.8.MIL
Peel Strength	2.7N/CM	25oz/In
Tensile Strength	40N/CM	22lbs/In
Elongation	50%	50%
Heat Resistance (Short Term)	290°C	554°C
Heat Resistance	230°C	446°C
Appearance	Amber	Amber

Product Code:	Description:	Size (mm):	Additional Notes:
1503246	High Temperature Masking Tape	6	Per Roll (Ref: 051-0007)

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